

Features

High reliability

High radiant intensity

Peak wavelength $\lambda_p=940\text{nm}$

2.54mm Lead spacing

Low forward voltage

Pb Free

This product itself will remain within RoHS compliant version.



Application

Free air transmission system

Infrared remote control units with high power requirement

Smoke detector

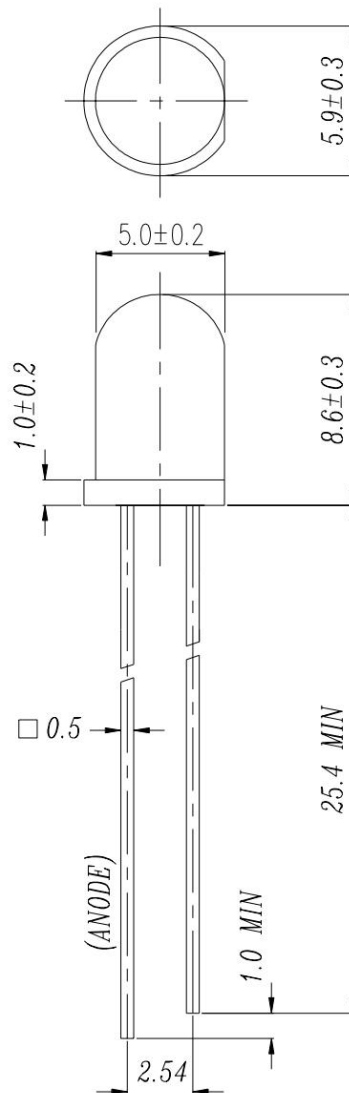
Infrared applied system

Compliance with EU REACH

Compliance Halogen Free(Br < 900ppm, Cl < 900ppm, Br+Cl < 1500ppm)

Description

Infrared Emitting Diode (KEL-504C) is a high intensity diode , molded in a water clear plastic package.The device is spectrally matched with phototransistor , photodiode and infrared receiver module.

PACKAGE DIMENSIONS

NOTES:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.25 mm (.010") unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.

ABSOLUTE MAXIMUM RATINGS AT TA =25°C

Parameter	Symbol	Rating	Units
Continuous Forward Current	I_F	100	mA
Peak Forward Current	I_{FP}	1.0	A
Reverse Voltage	V_R	5	V
Operating Temperature	T_{opr}	-40 ~ +85	°C
Storage Temperature	T_{stg}	-40 ~ +85	°C
Soldering Temperature	T_{sol}	260	°C
Power Dissipation at(or below)25°C Free Air Temperature	P_d	150	mW

Notes: *1: I_{FP} Conditions--Pulse Width \leq 100 μ s and Duty \leq 1%.

*2:Soldering time \leq 5 seconds.

ELECTRICAL OPTICAL CHARACTERISTICS AT TA=25°C

Parameter	Symbol	Condition	Min.	Typ.	Max.	Units
Radiant Intensity	Ee	I _F =20mA	7.8	15	--	mW/sr
		I _F =100mA Pulse Width≤100μs ,Duty≤1%	--	60	--	
		I _F =1A Pulse Width≤100μs ,Duty≤1%	--	450	--	
Peak Wavelength	λ _p	I _F =20mA	--	940	--	nm
Spectral Bandwidth	Δλ	I _F =20mA	--	45	--	nm
Forward Voltage	V _F	I _F =20mA		1.2	1.5	V
		I _F =100mA Pulse Width≤100μs ,Duty≤1%	--	1.4	1.85	
Reverse Current	I _R	V _R =5V	--	--	10	μA
View Angle	2θ _{1/2}	I _F =20mA	--	15	--	deg

Typical Electro-Optical Characteristics Curves

Fig.1 Forward Current vs. Ambient Temperature

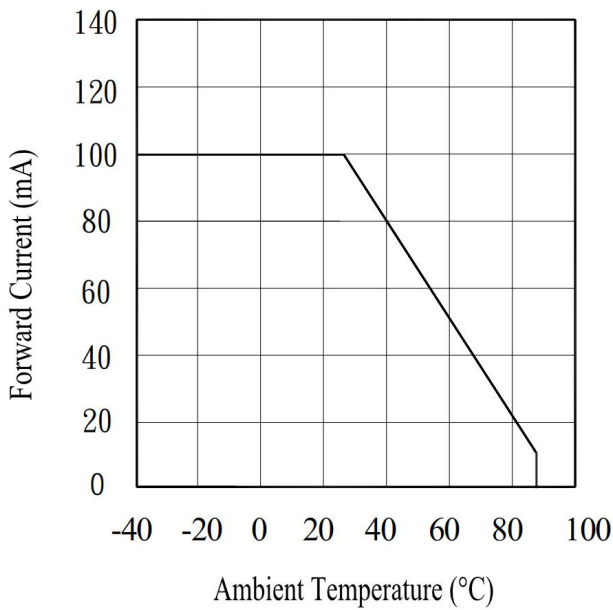


Fig.2 Spectral Distribution

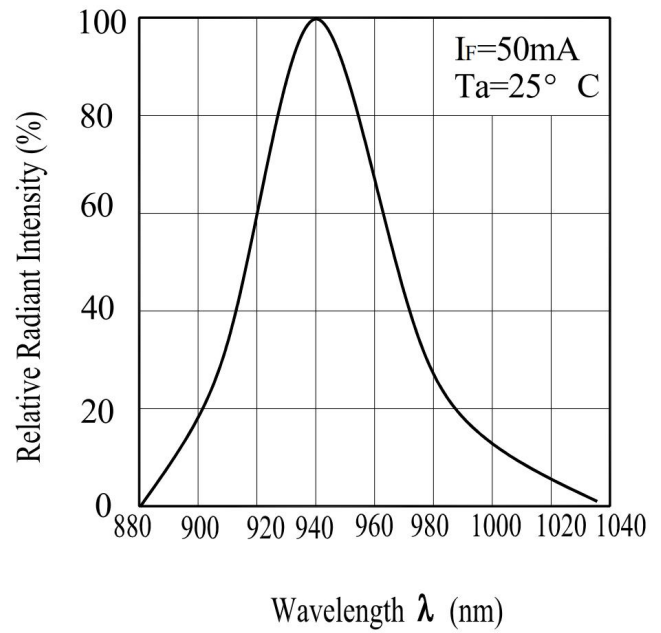


Fig.3 Peak Emission Wavelength vs. Ambient Temperature

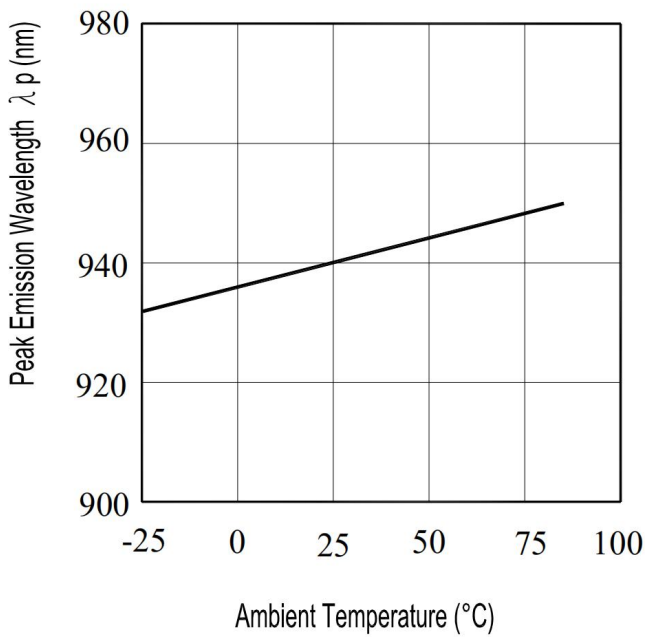
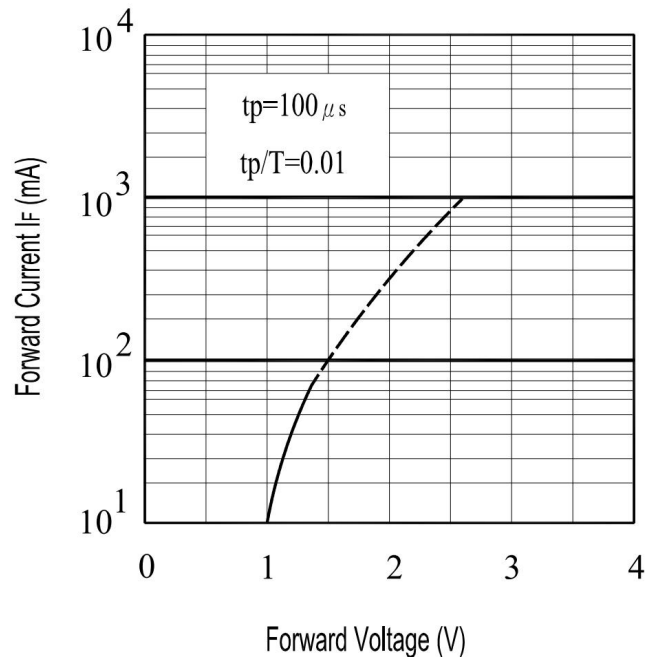


Fig.4 Forward Current vs. Forward Voltage



Typical Electro-Optical Characteristics Curves

Fig.5 Relative Intensity vs.

Forward Current

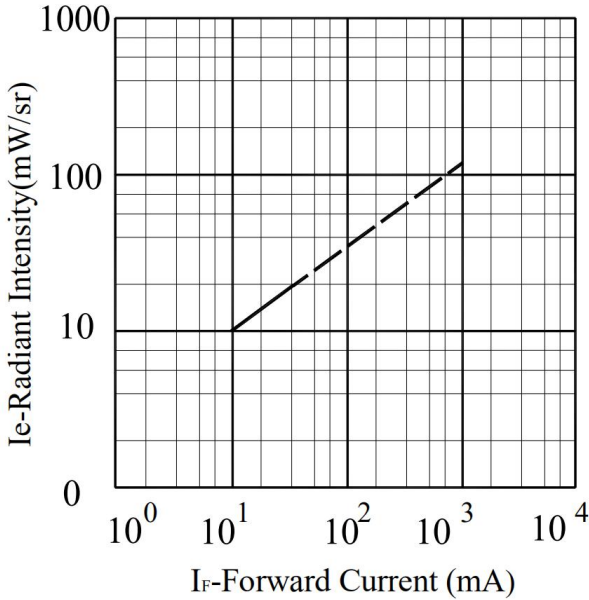


Fig.6 Relative Radiant Intensity vs.

Angular Displacement

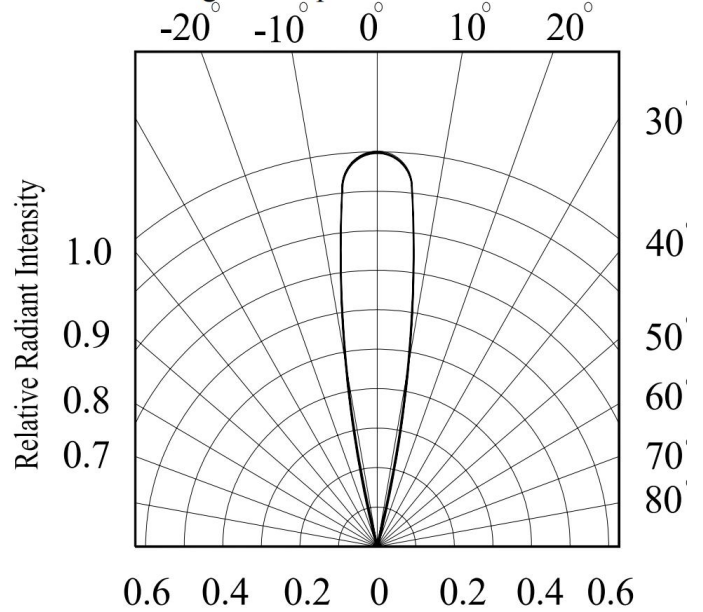


Fig.7 Relative Intensity vs.

Ambient Temperature(°C)

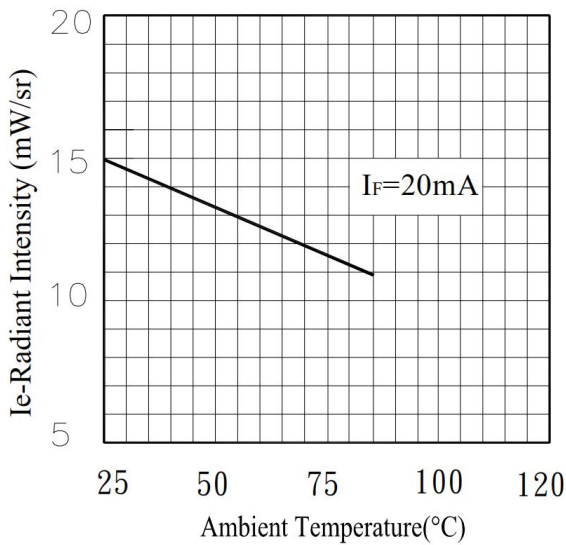
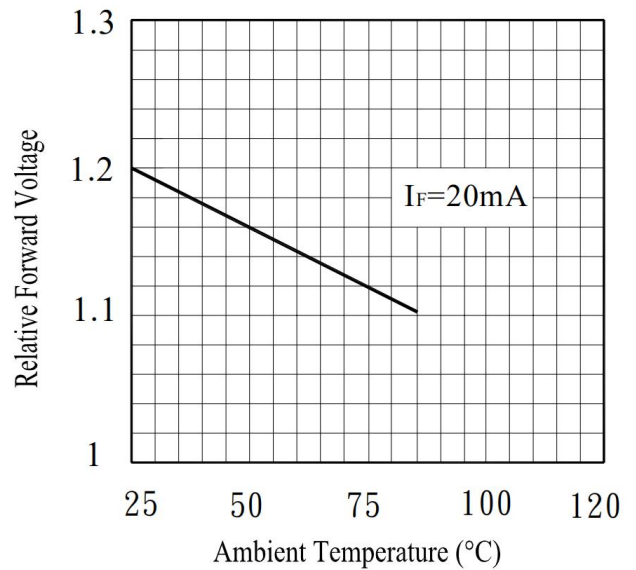


Fig.8 Forward Current vs.

Ambient Temperature(°C)



Reliability Test Item And Condition

The reliability of products shall be satisfied with items listed below.

Confidence level : 90%

LTPD : 10%

NO.	Item	Test Conditions	Test Hours/ Cycles	Sample Sizes	Failure Judgement Criteria	Ac/Re
1	Solder Heat	TEMP. : 260°C±5°C	10secs	22pcs		0/1
2	Temperature Cycle	H : +100°C 15mins ↕ 5mins L : -40°C 15mins	300Cycles	22pcs	$I_R \geq U \times 2$ $E_e \leq L \times 0.8$ $V_F \geq U \times 1.2$	0/1
3	Thermal Shock	H : +100°C 5mins ↕ 10secs L : -10°C 5mins	300Cycles	22pcs	U : Upper Specification	0/1
4	High Temperature Storage	TEMP. : +100°C	1000hrs	22pcs	Limit L : Lower	0/1
5	Low Temperature Storage	TEMP. : -40°C	1000hrs	22pcs	Specification Limit	0/1
6	DC Operating Life	$I_F = 20\text{mA}$	1000hrs	22pcs		0/1
7	High Temperature/ High Humidity	85°C / 85% R.H	1000hrs	22pcs		0/1

Packing Quantity Specification

1. 1000Pcs/1Bag,8 Bag/1Box
2. 4Boxes/1Carton

Label Form Specification

製品名 PRODUCT	
コードNo. CODE No.	
数量 Q'TY	
ロットNo. LOT No.	
備考 REMARKS	
	

- PRODUCT: Part Number
- CODE NO.: Product Serial Number
- QTY: Packing Quantity
- LOT No: Lot Number
- REMARKS:Remarks

Notes**Lead Forming**

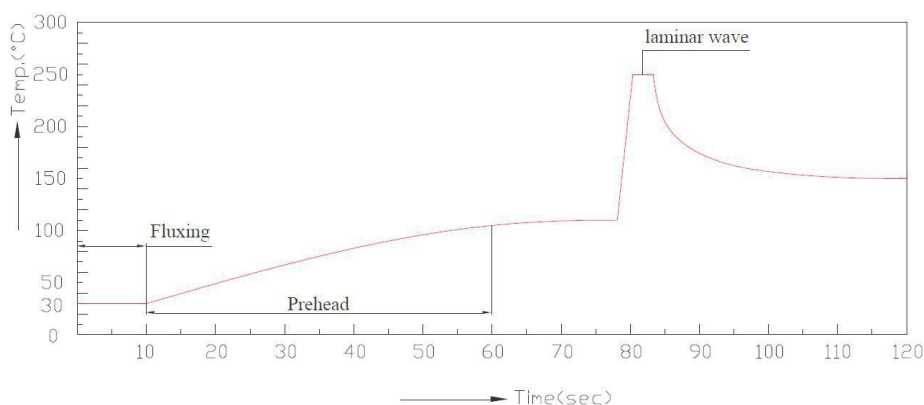
1. During lead formation, the leads should be bent at a point at least 3mm from the base of the epoxy bulb.
2. Lead forming should be done before soldering.
3. Avoid stressing the LED package during leads forming. The stress to the base may damage the LED's characteristics or it may break the LEDs.
4. Cut the LED lead frames at room temperature. Cutting the lead frames at high temperatures may cause failure of the LEDs.
5. When mounting the LEDs onto a PCB, the PCB holes must be aligned exactly with the lead position of the LED. If the LEDs are mounted with stress at the leads, it causes deterioration of the epoxy resin and this will degrade the LEDs.

Soldering

- Careful attention should be paid during soldering. When soldering, leave more than 3mm from solder joint to epoxy bulb, and soldering beyond the base of the tie bar is recommended.
- Recommended soldering conditions:

Hand Soldering		DIP Soldering	
Temp. at tip of iron	300°C Max. (30W Max.)	Preheat temp.	100°C Max. (60 sec Max.)
Soldering time	3 sec Max.	Bath temp. & time	260 Max., 5 sec Max
Distance	3mm Min.(From solder joint to epoxy bulb)	Distance	3mm Min. (From solder joint to epoxy bulb)

3. Recommended soldering profile



- Avoiding applying any stress to the lead frame while the LEDs are at high temperature particularly when soldering.
- Dip and hand soldering should not be done more than one time
- After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.
- Although the recommended soldering conditions are specified in the above table, dip or hand soldering at the lowest possible temperature is desirable for the LEDs.
- Wave soldering parameter must be set and maintain according to recommended temperature and dwell time in the solder wave.

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